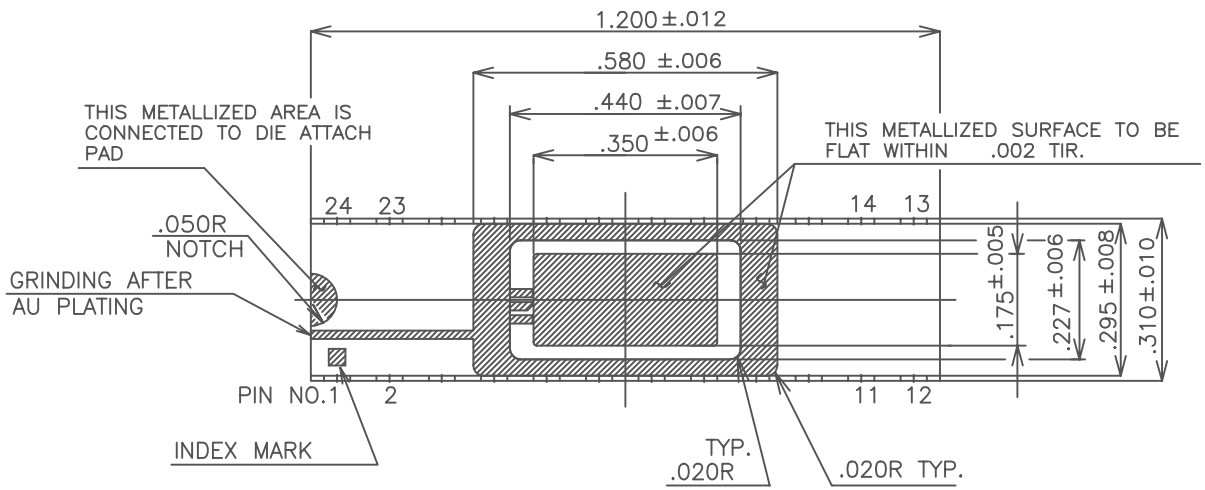
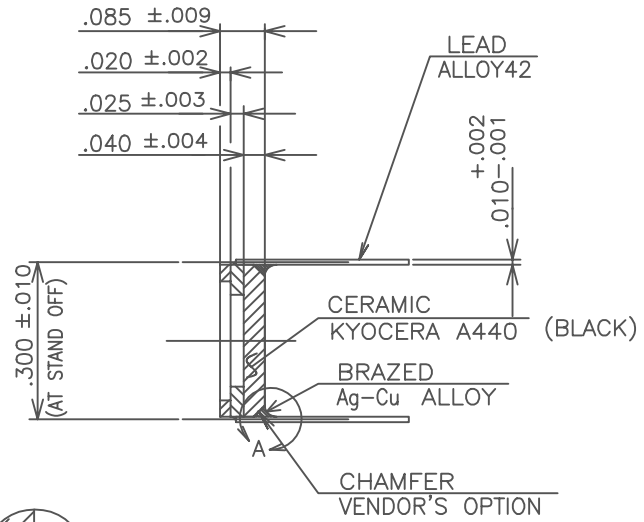
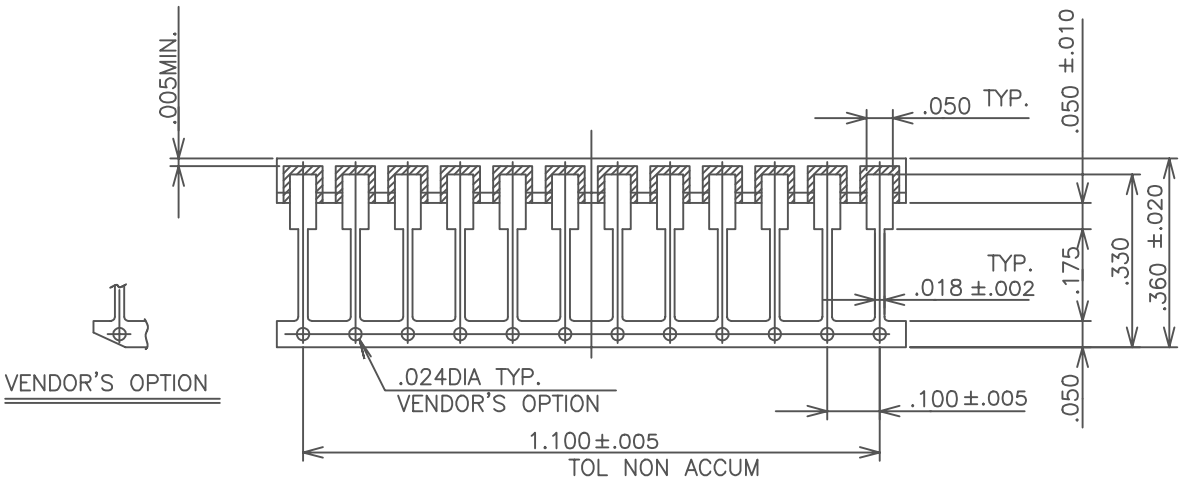






NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.30 OHMS AMX.
6. THE SEAL RING IS CONNECTED TO THE ALIGNMENT MARKS INTERNALLY BY VIA HOLES.

SB024Z092-1 S=0 D=0

MODIFICATION	CHANGED	DATE	DRAWN	CHECKED	APPROVED

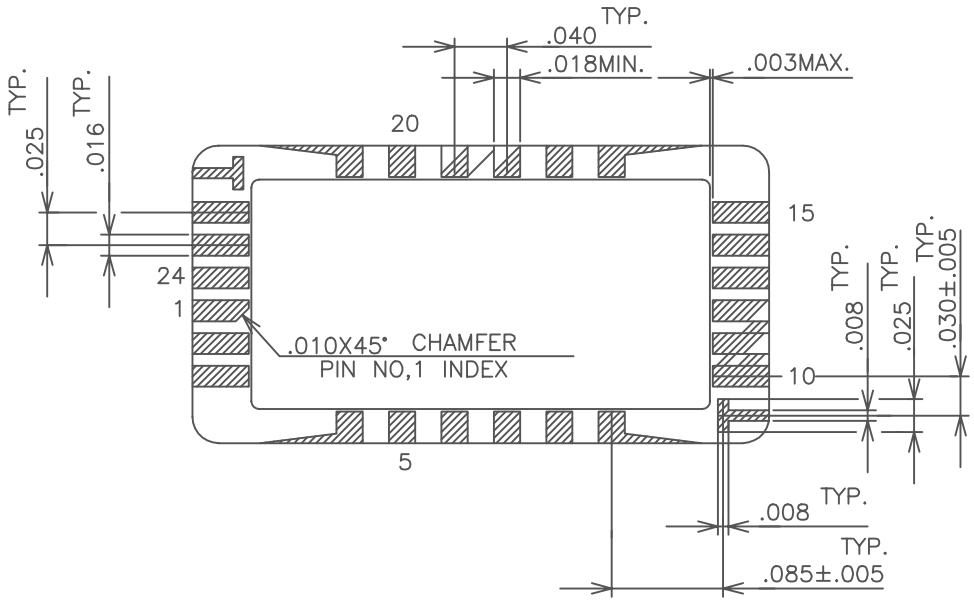
NAME: 24 LEAD SIDE BRAZED PACKAGE
SCALE 4/1
MATERIAL AS INDICATED
TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION

DRAWN	CHECKED	APPROVED	DATE
S.SH	S.T / T.A	M.K	FEB.07.91

KYOCERA CORPORATION KYOTO JAPAN

DRAWING NO. KD-S91092

SHEET 1/2



BONDING PATTERN

MODIFICATION							NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
							24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.SH	S.T / T.A	M.K	FEB.07.'91
							SCALE 10/1	MATERIAL				
							KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S91092			SHEET 2/2
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			THIRD ANGLE PROJECTION				